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(54) LAMINATE OF POLYIMIDE AND CONDUCTOR LAYER AND MULTILAYER INTERCONNECTION BOARD USING THE SAME AS WELL AS ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a laminate having excellent adhesive properties between a conductor and a polyimide film without using physical surface roughing and an adhesive metal layer.

SOLUTION: The laminate of a polyimide obtained by directly forming at least one conductor layer on the surface of a thermoplastic polyimide and a conductor layer is pressurized and heat treated, heat fusion bonded to strengthen an adhesive strength of the polyimide and the conductor layer.

LEGAL STATUS

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